

**REMARKS**

Claims 1, 4, and 9-12 are pending. Claims 2, 7, 8 and 13-17 are cancelled by way of this Amendment. Claims 3, 5 and 6 were previously cancelled.

**I. Claim to Priority:**

The Examiner has again **not** acknowledged Applicants' claim to foreign priority, and has not indicated receipt of the certified copy of the Priority Document. A review of the USPTO PAIR Website indicates that the Office did receive the certified copy of the Priority Document that was filed on December 8, 2003.

**Applicants respectfully request that the Examiner formally acknowledge receipt of the claim to priority in the next Office Action.**

**II. Drawings:**

The Examiner has again **not** indicated acceptance of the replacement drawings filed on June 16, 2004. **Applicants request that the Examiner indicate acceptance of the drawing figures in the next Office Action.**

**III. IDS:**

The Examiner has **not** returned the initialed Form PTO/SB/08 filed with the Information Disclosure Statement on December 8, 2003. However, the Examiner has returned the initialed Form PTO/SB/08 filed with the Information Disclosure Statement filed on October 27, 2006.

**Applicants request that the Examiner return the initialed Form PTO/SB/08 for the December 8, 2003 IDS.**

IV. Claim Objection:

Claim 10 is objected to because of informalities. Applicants amend claim 10 accordingly.

V. Claim Rejections:

Claims 1, 2, 4 and 7-17 are rejected under 35 U.S.C. § 102(b) as being anticipated by *newly* cited Nakamura (6,313,526).

The Present Invention

Applicants amend claim 1 to clarify that a tape carrier for TAB comprises a carrying support film and individual pieces of flexible wiring boards mounted at regular intervals on the carrying support film, and in which an entire surface of each of the flexible wiring boards and an entire surface of a mounting portion of the carrying support film are bonded to each other through an adhesive agent.

This amendment to claim 1 is fully supported by the originally filed specification (see specification at page 18), and, thus, not addition of a new matter.

In a tape carrier for TAB of the present invention, individual piece like flexible wiring boards are mounted on a carrying support film, and therefore, it is possible to avoid flexible wiring boards, which are defective products initially, from being mounted on the carrying support film. For this reason, it is not necessary to punch a defective flexible wiring board together with the carrying support film and to replace it with a non-defective flexible wiring board in a subsequent step, and it is possible to prevent an unevenness in height from being formed between respective flexible wiring boards due to the replacement. As a result, it is possible to improve the yield on continuous production by a simple configuration, and it is

possible to ensure high connection reliability while improvement in production efficiency and reduction in production cost can be attained.

With the present invention, an entire surface of the flexible wiring board and an entire surface of a mounting portion of a carrying support film can be mounted to each other, thus, providing improved stability and facilitating in the height evenness for the respective boards on the support film. As mentioned above, this levelness in the boards improves production quality.

Comparison of claim 1 and the cited art

Generally, in the prior art, flexible wiring boards are created on the support film directly. Thus, when a defective flexible wiring board is detected, it must be punched out and replaced. This causes an unevenness in the heights of the flexible wiring boards, thereby downgrading production yield during subsequent connection operations.

With the present invention, the flexible wiring boards are mounted on the support films. In other words, they are created first, and judged for defects before being mounted on the support film. By mounting flexible wiring boards on the support films, the subsequent unevenness due to replacing defective boards is prevented.

Moreover, the mounting of the boards on the support film is even and consistent due to the fact that the entire surface of the wiring boards and the entire surface of the mounting portions of the support film are bonded to each other. With this structure, the board can be mounted on the support film so that the adhesive agent has a uniform thickness (see page 18 of the specification). This contributes to a more even level for the wiring boards placed on the support film.

Nakamura '526 fails to disclose this structure since bores (openings) 32 are formed at the mounting portions, each to a size substantially equal to the size of the IC chip 4, at a position

corresponding to a position at which the IC chip 4 is to be installed. Nakamura '526 specifically provides the bores to facilitate the separation of the film 30 and the film 33 from each other. (See cols. 8-9.)

Thus, Nakamura does not disclose that an entire surface of the wiring board and an entire surface of the mounting portion of the support film are bonded to each other. Rather, only a portion of the surface of the flexible wiring board is mounted to the alleged support film, since that portion of the board facing the bore 32 has no surface to mount on.

In view of the foregoing, claim 1 is patentable.

The remaining rejections are directed to the dependent claims. These claims are patentable at least by virtue of their dependency from claim 1.

### **Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

AMENDMENT UNDER 37 C.F.R. § 1.111  
Application No.: 10/728,911

Attorney Docket No.: Q78886

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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